LG Electronics Inc.
1000 Sylvan Avenue
Englewood Cliffs, NJ 07632

Date: **September 13, 2010**

Federal Communications Commission
Authorization and Evaluation Division
7435 Oakland Mills Road,
Columbia, MD 21046

SUBJECT: LG Electronics USA
FCC ID/IC : BEJC900K, 2703C-C900B
Class II Permissive change
Original FCC Grant Date: August 24, 2010, Original IC Grant Date: August 26, 2010

Gentlemen:

Transmitted herewith, on behalf of LG Electronics USA is an application for a Class II Permissive Change Certification of a Cellular/PCS GSM/EDGE and WCDMA Phone with Bluetooth & WLAN.

The device is electrically identical to the previously certified Cellular/PCS GSM/EDGE and WCDMA Phone with Bluetooth & WLAN except for the proposed modifications changes listed as below.

ITEM

1. Antenna Pattern
   : To improve TIS Performance
2. SUB PCB(1)PCB Shape, (2)Add damper, (3)BT/WLAN Antenna feeding PAD)
   1,2: ESD Performance, 3: To improve BT/WLAN Radiation Performance
3. PCB Shield can Type
   : Due to durability
4. PCB Divided voltage of touch IC
   : To reduce ghost noise, divided voltage of touch IC form 3.0V into 2.6 V and 3.0V
5. PCB Revmoved LEDs for caps and function
   : It's mechanically difficult to meet the brightness of LEDs.
6. PCB Changed micro USB connector
   : Changed micro USB connector to reverse type
7. PCB Added earphone logic
   : Added earphone logic in order to wake the system up from sleep state up form Sleep state by hook, volume up or volume down of earphone
8. PCB Added LDO
   : The LDO in PMIC for keycoder IC is used to touch IC. So, a discrete LDO is newly added to keycoder IC.
9. PCB LCD MDDI Type2
   :To meet MS requirement for 60fps quality of LCD, changed to Type2 form Type1. Two data lines and one EMI filter added

10. LCD
    :To reduce LCD noise in W850 band and TIS improvement,
    To improve assembly efficiency
11. Battery cover
    : Added unit On battery coverto improveGPS Antenna Performance(contact to SIM Socket)
12. Shield can
    : Changed shield canto stick on PID label
13. Cover, Front: Created ribsTo prevent COVER FRONTdeformation
14. Cover, REAR COVER, FORNT: Created ribs Around Ear jack To prevent Ear Jack crackAfter Drop Test
15. Cover rear: Deleted the holeFor Drop Test
16. Frame: Changed Label A/S positionAnd created a hole
17. Cover rear: Deleted the holeFor Drop Test
18. Frame: Changed Label A/S positionAnd created a hole
19. Cover rear: Added ribsTo improve Drop Test Issue.To prevent Cover Rear deformation

Should you have any questions or comments concerning the above, please contact the undersigned.

Jae Cheon (J.C.) Lee
General Manager
LG Electronics USA